WTMH116T16

SCR Module

Rev.02 - 08 December 2023 Product data sheet

1. General description

Planar passivated Silicon Controlled Rectifier (SCR) module in WeEnPACK-20mm (TO-240AA) for use in applications requiring high blocking voltage capability, high inrush current capability and high thermal cycling performance

2. Features and benefits

- High blocking voltage capability
- High thermal cycling performance
- Planar passivated for voltage ruggedness and reliability
- Package meets UL certification
- Package is RoHS compliant
- Industry standard outline
- Soldering pins for PCB mounting
- Copper base plate
- Cathode Kelvin contacts provided
- UL1557 certified (Document number E346397)

3. Applications

- Softstart AC motor control
- DC Motor control
- AC power control
- Power converter
- Temperature control
- Lighting control

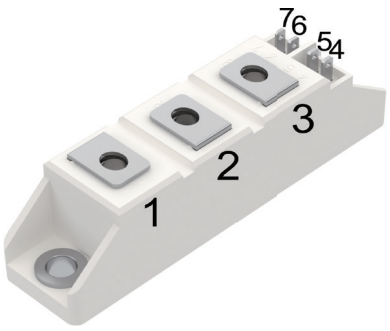
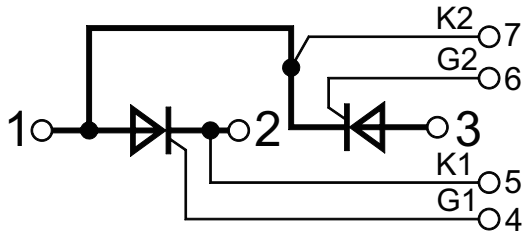
4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Notes	Values			Unit
Absolute maximum rating							
V_{DRM}	repetitive peak forward voltage			1600			V
V_{RRM}	repetitive peak reverse voltage			1600			V
$I_{T(RMS)}$	RMS on-state current	half sine wave		182			A
I_{TSM}	non-repetitive peak on-state current	half sine wave; $T_{j(init)}$ = 25 °C; t_p = 10 ms		2300			A
		half sine wave; $T_{j(init)}$ = 130 °C; t_p = 10 ms		2000			A
		half sine wave; $T_{j(init)}$ = 25 °C; t_p = 8.3 ms		2530			A
		half sine wave; $T_{j(init)}$ = 130 °C; t_p = 8.3 ms		2200			A
Symbol	**Parameter**	**Conditions**	**Notes**	**Min**	**Typ**	**Max**	**Unit**
Static characteristics							
I_{GT}	gate trigger current	V_D = 12 V; I_T = 0.1 A; T_j = 25 °C		30	-	100	mA
V_{GT}	gate trigger voltage	V_D = 12 V; I_T = 0.1 A; T_j = 25 °C		-	0.75	1.2	V
V_T	on-state voltage	I_T = 116 A; T_j = 25 °C		-	-	1.29	V

5. Pinning information

Table 2. Pinning information

Simplified outline	Graphic symbol
	

6. Ordering information

Table 3. Ordering information

Type number	Package Name	Orderable part number	Packing method	Small packing quantity	Package version	Package issue date
WTMH116T16	WeEnPACK-20mm	WTMH116T16T	Tray	12	WeEnPACK-20mmPHB-A	27-Jun-2023

7. Marking

Table 4. Marking codes

Type number	Marking codes
WTMH116T16	WTMH116T16

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Notes	Values	Unit
V_{DRM}	repetitive peak forward voltage			1600	V
V_{RRM}	repetitive peak reverse voltage			1600	V
$I_{T(AV)}$	average on-state current	half sine wave		116	A
$I_{T(RMS)}$	RMS on-state current	half sine wave		182	A
I_{TSM}	non-repetitive peak onstate current	half sine wave; $T_{j(init)}$ = 25 °C; t_p = 10 ms		2300	A
		half sine wave; $T_{j(init)}$ = 130 °C; t_p = 10 ms		2000	A
		half sine wave; $T_{j(init)}$ = 25 °C; t_p = 8.3 ms		2530	A
		half sine wave; $T_{j(init)}$ = 130 °C; t_p = 8.3 ms		2200	A
I^2t	I^2t for fusing	t_p = 10 ms; sine-wave pulse		26.4	kA^2s
dI_T/dt	rate of rise of on-state current	I_G = 200 mA; T_j = 130 °C		200	A/µs
I_{GM}	peak gate current			10	A
V_{RGM}	peak reverse gate voltage			5	V
P_{GM}	peak gate power			20	W
$P_{G(AV)}$	average gate power	over any 20 ms period		0.5	W
T_{stg}	storage temperature			-40 to 130	°C
T_j	junction temperature			-40 to 150	°C

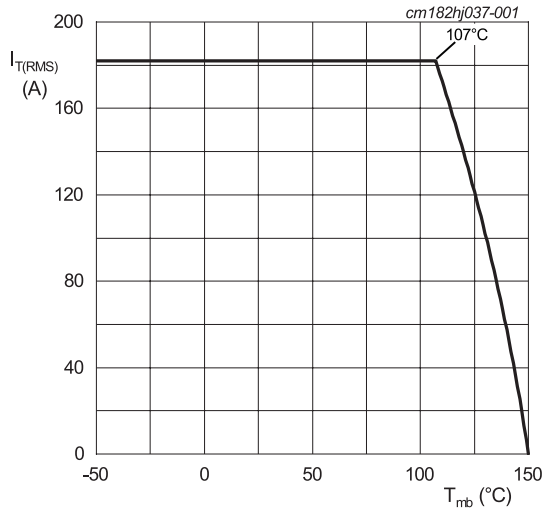
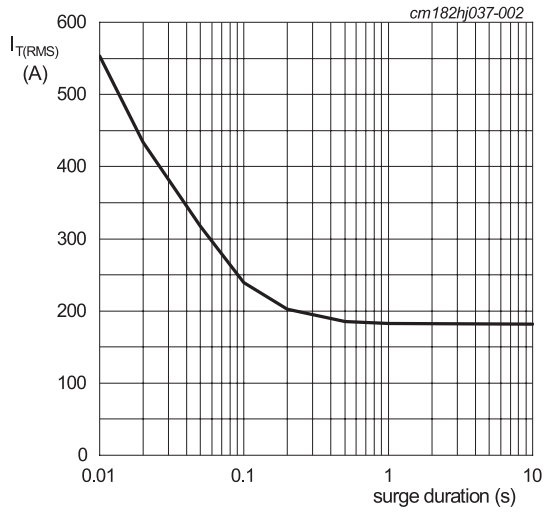


Fig. 1. RMS on-state current as a function of mounting base temperature; maximum values



f = 50 Hz; T_{mb} = 107 °C

Fig. 2. RMS on-state current as a function of surge duration; maximum values

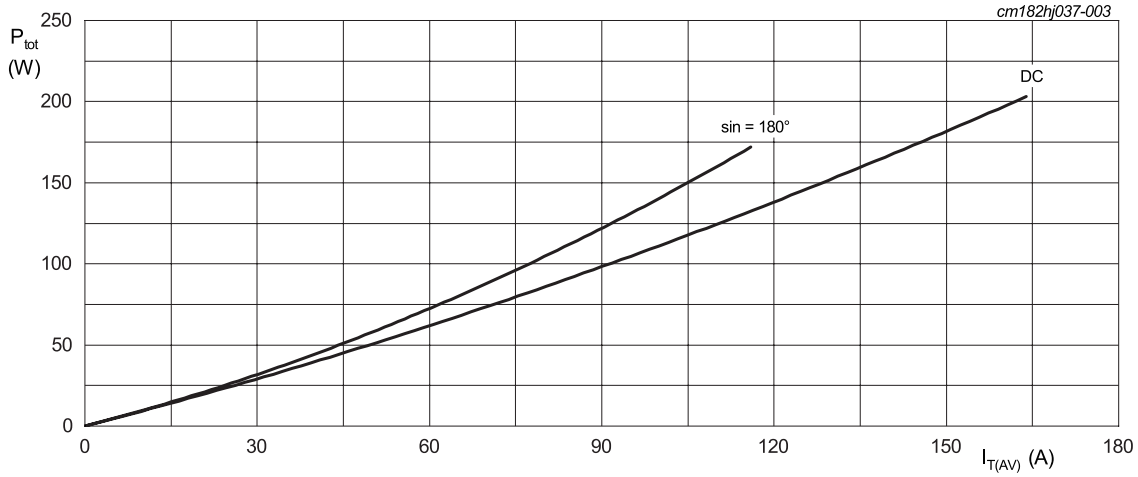
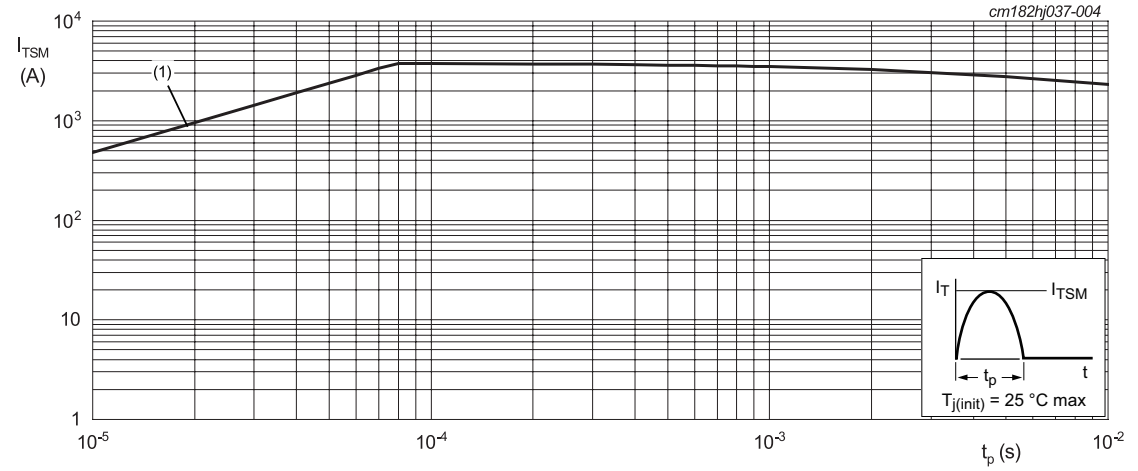


Fig. 3. Total power dissipation as a function of average on-state current; maximum values; per thyristor



$t_p \leq 10$ ms

(1) dI_T/dt limit

Fig. 4. Non-repetitive peak on-state current as a function of pulse width; maximum values

9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$R_{th(j-c)}$	thermal resistance from junction to case	per thyristor		-	-	0.25	K/W
		per module		-	-	0.125	K/W
$R_{th(j-h)}$	thermal resistance from junction to heatsink	per thyristor		-	-	0.48	K/W
		per module		-	-	0.24	K/W

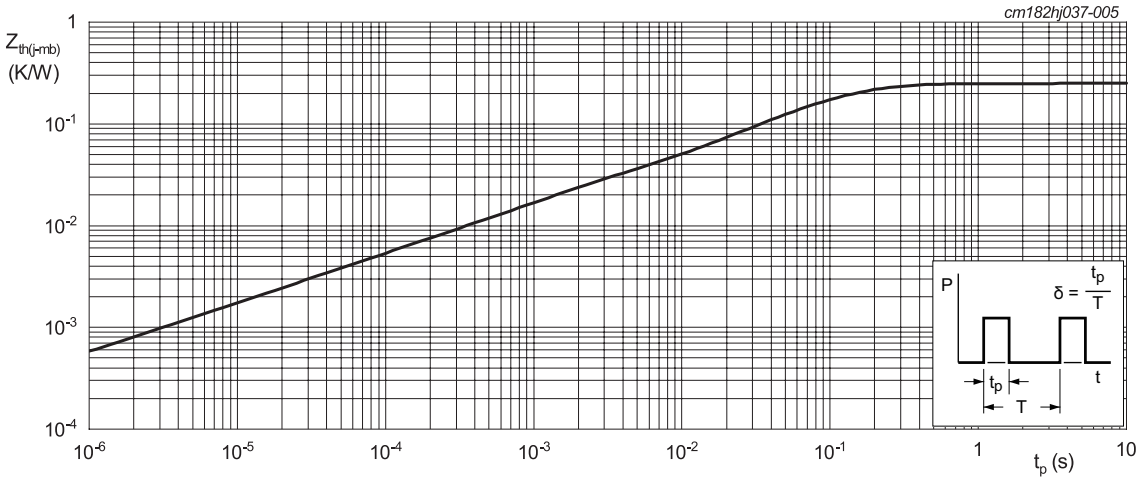


Fig. 5. Transient thermal impedance from junction to mounting base as a function of pulse duration

10. Package characteristics

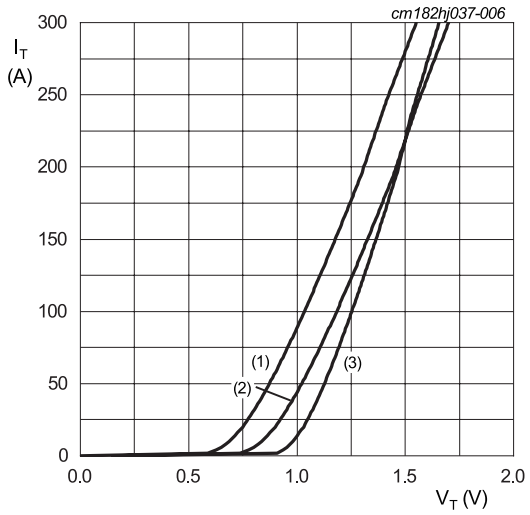
Table 7. Isolation characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
V_{isol}	isolation voltage	50/60 Hz; RMS; $I_{ISOL} \leq 1$ mA; t = 1 second; AC		-	-	3600	V
		50/60 Hz; RMS; $I_{ISOL} \leq 1$ mA; t = 1 minute; AC		-	-	3000	V

11. Characteristics

Table 8. Characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
Static characteristics							
I_{GT}	gate trigger current	V_D = 12 V; I_T = 0.1 A; T_j = 25 °C		30	-	100	mA
V_{GT}	gate trigger voltage	V_D = 12 V; I_T = 0.1 A; T_j = 25 °C		-	0.75	1.2	V
		V_D = 2/3 V_{DRM} V; I_T = 0.1 A; T_j = 130 °C		0.25	0.4	-	V
I_{GD}	gate non-trigger current	T_j = 130 °C		-	-	8	mA
V_{GD}	gate non-trigger voltage	T_j = 130 °C		-	-	0.2	V
I_L	latching current	V_D = 12 V; I_T = 0.1 A; T_j = 25 °C		-	-	300	mA
I_H	holding current	V_D = 12 V; T_j = 25 °C		-	-	200	mA
V_T	on-state voltage	I_T = 116 A; T_j = 25 °C		-	-	1.29	V
		I_T = 300 A; T_j = 25 °C		-	-	1.65	V
V_{TO}	threshold voltage	T_j = 130 °C		-	-	0.9	V
r_T	slope resistance	T_j = 130 °C		-	-	2.0	mΩ
I_D	off-state current	V_D = 1600 V; T_j = 25 °C		-	-	100	µA
		V_D = 1600 V; T_j = 130 °C		-	2	10	mA
		V_D = 1600 V; T_j = 150 °C		-	10	-	mA
I_R	reverse current	V_R = 1600 V; T_j = 25 °C		-	-	100	µA
		V_R = 1600 V; T_j = 130 °C		-	2	10	mA
		V_R = 1600 V; T_j = 150 °C		-	10	-	mA
Dynamic characteristics							
dV_D/dt	rate of rise of off-state voltage	V_{DM} = 1072 V; T_j = 130 °C; (V_{DM} = 67% of V_{DRM}); exponential waveform; gate open circuit		1500	-	-	V/µs
t_{gt}	gate-controlled turn-on time	I_{TM} = 40 A; V_D = 800 V; I_G = 100 mA; $(dI_G/dt)_M$ = 1 A/µs; T_j = 25 °C		-	2	-	µs



V_{TO} = 0.9 V; r_T = 0.002 Ω
(1) T_j = 130 °C; typical values
(2) T_j = 130 °C; maximum values
(3) T_j = 25 °C; maximum values

Fig. 6. On-state current as a function of on-state voltage

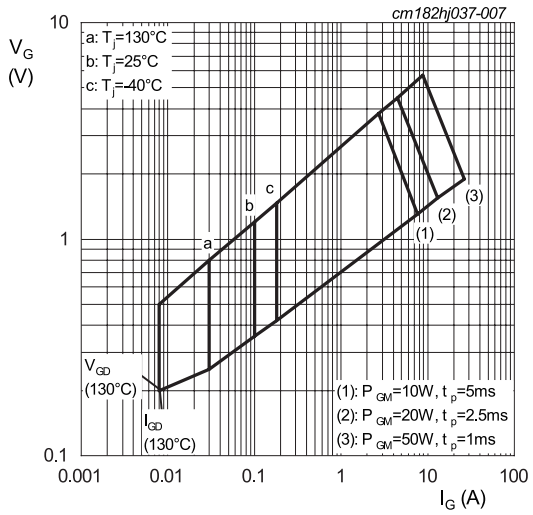
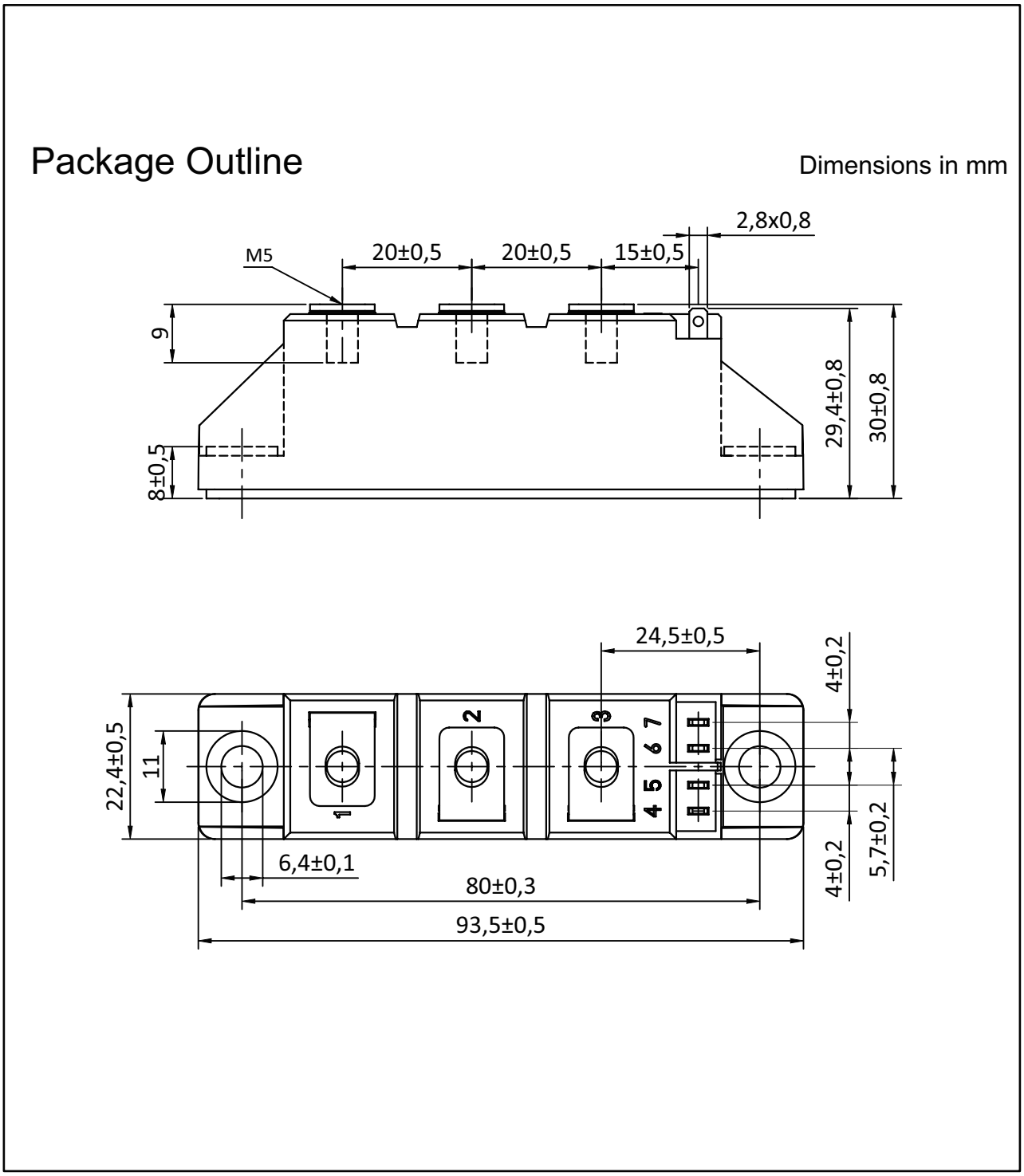


Fig. 7. Gate voltage as a function of gate current

12. Package outline

WeEnPack-20mm



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Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
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